





United States Patent and Trademark Office

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 2023I
WWW.uspto.gov

Bib Data Sheet

CONFIRMATION NO. 8431

SERIAL NUMBER 09/934,474	FILING DATE 08/23/2001 RULE	CLA \$		GROUP ART U		T UNIT	ATTORNEY DOCKET NO. 50090-334	
Yoshio Hayashi ** CONTINUING DATA ** FOREIGN APPLICA	aki, Tokyo, JAPAN; de, Tokyo, JAPAN; A ************************************							
	3478 11/29/2000 GN FILING LICENSE	GRANTED						
Foreign Priority claimed 35 USC 119 (a-d) conditions yes no Met after Allowance Verified and Acknowledged Examing & Initials			ATE OR DUNTRY JAPAN			TOTA CLAII 20	MS	INDEPENDENT CLAIMS 2
ADDRESS McDermott, Will & Eme 600 13th Street, N.W. Washington ,DC 2000	•							
TITLE Polishing solution supp semiconductor substra	oly system, method of s te and method of manu	upplying poli	shing solu niconduct	tion, ap or devi	oparatus ce	s for and	meth	od of polishing
FILING FEE FEES RECEIVED No	: Authority has been gi	n given in Paper e/credit DEPOSIT ACCOUNT			All Fees 1.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other Credit			